

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (original): An inorganic powder having a frequency-size distribution with multiple peaks, wherein the peaks are present at least in the particle size regions from 0.2 to 2 μm and from 2 to 63 μm .
2. (original): The inorganic powder as claimed in claim 1, wherein the maximum particle size is 63 μm or less, the average particle size is from 4 to 30 μm , and the mode size is from 2 to 35 μm .
3. (original): The inorganic powder as claimed in claim 1, wherein the percentage of particles having a particle size of less than 2 μm is from 0 to 20 mass% and the mode size of particles having a particle size of less than 2 μm is from 0.25 to 1.5 μm .
4. (original): The inorganic powder as claimed in claim 1, wherein the percentage of particles having a particle size of 8 μm or more is from 44 to 90 mass%.
5. (original): The inorganic powder as claimed in claim 1, wherein the percentage of particles having a particle size of from 2 to 8 μm is from 0 to 15 mass%.

6. (original): The inorganic powder as claimed in claim 1, wherein the percentage of particles having a particle size of from 2 to 8 μm is from 32 to 45 mass%.

7. (original): The inorganic powder as claimed in claim 1, wherein the spheroidicity is from 0.68 to 0.95 and the spheroidization ratio is from 0.63 to 0.95.

8. (original): The inorganic powder as claimed in claim 1, wherein the spheroidicity of particles having a particle size of less than 2 μm is from 0.5 to 0.95 and the spheroidization ratio thereof is from 0 to 0.9.

9. (original): The inorganic powder as claimed in claim 1, wherein the spheroidicity of particles having a particle size of 8 μm or more is from 0.7 to 0.95 and the spheroidization ratio thereof is from 0.7 to 0.95.

10. (original): The inorganic powder as claimed in claim 1, wherein the thermal conductivity of the inorganic powder in the single crystal state is 30 W/m·K or more.

11. (currently amended): The inorganic powder as claimed in claim 1 ~~any one of claims 1 to 10~~, which is an alumina powder.

12. (original): The inorganic powder as claimed in claim 11, wherein the α alumina crystal phase fraction of the alumina powder is from 30 to 75 mass%.

13. (original): The inorganic powder as claimed in claim 11, wherein the α alumina crystal phase fraction of the particle of less than 2 μm is from 90 to 100 mass%.

14. (original): The inorganic powder as claimed in claim 11, wherein the α alumina crystal phase fraction of the particle of 8 μm or more is from 30 to 70 mass%.

15. (original): The inorganic powder as claimed in claim 1, wherein the content of metal aluminum is 0.05 mass% or less.

16. (original): The inorganic powder as claimed in claim 1, wherein the content of sulfate ion is 15 ppm or less.

17. (original): The inorganic powder as claimed in claim 1, wherein the content of chlorine ion is 15 ppm or less.

18. (original): The inorganic powder as claimed in claim 1, wherein the content of Fe_2O_3 is 0.03 mass% or less.

19. (original): The inorganic powder as claimed in claim 1, which contains substantially no particles of less than 50 nm.

20. (original): The inorganic powder as claimed in claim 1, which is subjected to surface-hydrophobing treatment with at least one surface-treating agent selected from silane-based coupling agent and titanate-based coupling agent.

21. (currently amended): A resin composition filled with the inorganic powder described in claim 1~~any one of claims 1 to 20~~.

22. (original): The resin composition as claimed in claim 21, wherein from 50 to 90 mass% of the inorganic powder is filled.

23. (currently amended): The resin composition as claimed in claim 21~~or 22~~, wherein when the resin composition is formed into a thin-film insulating resin composition with a thickness of 40 to 90 μm , the dielectric breakdown strength as measured by a dielectric breakdown voltage test prescribed in JIS C2110 is 39 kV/mm or more.

24. (currently amended): A circuit board for mounting on automobiles, using the resin composition described in claim 21~~any one of claims 21 to 23~~.

25. (currently amended): A circuit board for mounting on electronic devices, using the resin composition described in claim 21~~any one of claims 21 to 23~~.

26. (currently amended): A high thermally conductive member for installation in electronic devices, using the resin composition described in claim 21~~any one of claims 21 to 23~~.

27. (currently amended): A high thermally conductive member for electronic components, using the resin composition described in claim 21~~any one of claims 21 to 23~~.

28. (currently amended): The high thermally conductive member as claimed in claim 26~~or 27~~, which is in a sheet form.

29. (currently amended): The high thermally conductive member as claimed in claim 26~~or 27~~, which is in a form of gel or paste.

30. (currently amended): The high thermally conductive member as claimed in claim 26~~or 27~~, which is underfill-agent type member.

31. (currently amended): The high thermally conductive member as claimed in claim 26~~or 27~~, which is applied by coating onto a heating portion of an elemental device.

32. (currently amended): A metal-based circuit board, a metal core-type circuit board and a structure body thereof, wherein the resin composition described in claim 21~~any one of claims 21 to 23~~ is used as a high thermally conductive member serving also as an insulating adhesive layer or the like.

33. (currently amended): A structure body of a high thermally conductive metal member-integrated electronic component, wherein a heat generating electronic component and a high thermally conductive metal member are bonded by using the high thermally conductive member described in claim 26~~any one of claims 26 to 31~~.

34. (currently amended): An LED circuit board using the high thermally conductive member described in claim 26~~any one of claims 26 to 31~~.

35. (currently amended): An automobile using the circuit board claimed in claim 32~~, or 34 or the structure body claimed in claim 32 or 33~~.

36. (currently amended): An electronic product using the circuit board claimed in claim 32~~, or 34 or the structure body claimed in claim 32 or 33~~.

Preliminary Amendment

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37. (currently amended): A light indicator using the circuit board claimed in claim 32, ~~or 34 or~~
~~the structure body claimed in claim 32 or 33.~~

38. (currently amended): A display device using the circuit board claimed in claim 32, ~~or 34 or~~
~~the structure body claimed in claim 32 or 33.~~